

INTERNATIONAL STANDARD

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**Surface mounting technology –
Part 3: Standard method for the specification of components for through hole
reflow (THR) soldering**

**Technique du montage en surface –
Partie 3: Méthode normalisée relative à la spécification des composants pour
le brasage par refusion à trous traversants (THR, Through Hole Reflow)**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SURFACE MOUNTING TECHNOLOGY –

Part 3: Standard method for the specification of components for through hole reflow (THR) soldering

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International Standard IEC 61760-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

CDV	Report on voting
91/856/CDV	91/898/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61760 series, under the general title *Surface mounting technology* can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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SURFACE MOUNTING TECHNOLOGY –

Part 3: Standard method for the specification of components for through hole reflow (THR) soldering

1 Scope and object

This part of IEC 61760 gives a reference set of requirements, process conditions and related test conditions to be used when compiling specifications of electronic components that are intended for usage in through hole reflow soldering technology.

The object of this standard is to ensure that components with leads intended for through hole reflow and surface mounting components can be subjected to the same placement and mounting processes. Hereto, this standard defines test and requirements that need to be part of any component generic, sectional or detail specification, when through hole reflow soldering is intended. Further this standard provides component users and manufacturers with a reference set of typical process conditions used in through hole reflow soldering technology.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60062, *Marking codes for resistors and capacitors*

IEC 60068 (all parts), *Environmental testing*

IEC 60068-2-20, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-21, *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-45:1980, *Basic environmental testing procedures – Part 2-45: Tests – Test XA and guidance: Immersion in cleaning solvents*
Amendment 1:1993

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-77, *Environmental testing – Part 2-77: Tests – Body strength and impact shock*

IEC 60068-2-82, *Environmental testing – Part 2-82: Tests – Test XW₁: Whisker test methods for electronic and electric components*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60286 (all parts), *Packaging of components for automatic handling*

IEC 60286-3, *Packaging of components for automatic handling – Part 3: Packaging of surface mount components on continuous tapes*

IEC 60286-4, *Packaging of components for automatic handling – Part 4: Stick magazines for electronic components encapsulated in packages of form E and G*

IEC 60286-5, *Packaging of components for automatic handling – Part 5: Matrix trays*

IEC 60749-20, *Semiconductor devices – Mechanical and climatic test methods – Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat*

IEC 61760-2, *Surface mounting technology – Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide*

IEC 62090, *Product package labels for electronic components using bar code and two-dimensional symbologies*

ISO 8601, *Data elements and interchange formats – Information interchange – Representation of dates and times*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 and the following apply.

3.1

terminal pitch

distance between the terminals of the component, either uniformly distributed or specifically defined

3.2

dewetting

condition that results when molten solder coats a surface and then recedes to leave irregularly-shaped mounds of solder that are separated by areas that are covered with a thin film of solder and with the basis metal not exposed

3.3

dissolution of metallization

process of dissolving metal or a plated metal alloy, usually by introduction of chemicals

NOTE For the purpose of this document standard, the dissolution of metallization also includes dissolution by exposure to molten solder.

3.4

pick-up force

dynamic force exerted on the body of a component – generally from above – and its seating plane during the pick-up of the component (e.g. from a tape or tray)

NOTE The maximum level is normally taken into account.

3.5

placement force

dynamic force exerted on the component body – generally from above – and its seating plane occurring during the period between the component's first contact with the substrate (or the soldering paste or adhesive, etc.) and its coming to rest

NOTE The maximum level is normally taken into account.